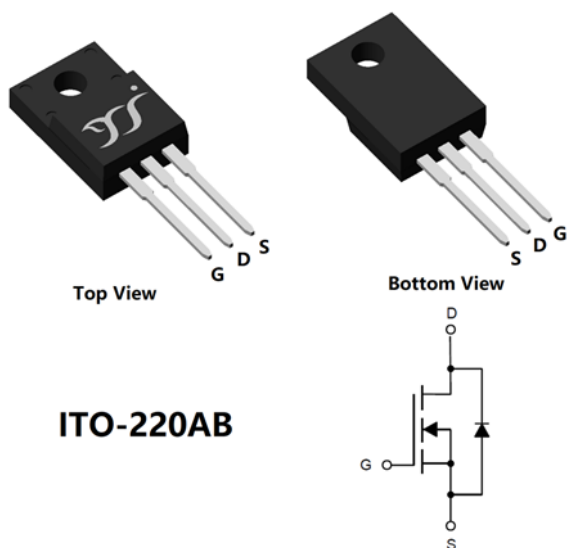


N-Channel Enhancement Mode Field Effect Transistor



Product Summary

• V_{DS}	600V
• I_D	11A
• $R_{DS(ON)}$ (at $V_{GS}=10V$)	<360m Ω
• 100% EAS Tested	
• 100% ∇V_{DS} Tested	
• ESD Level(HBM)	H1C

General Description

- Super Junction High Voltage MOSFET technology
- Ultra Low Gate Charge Cause Lower Driving Requirement
- Low On-resistance and Low Conduction Loss
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Power supply for black appliances

Limiting Values

Parameter	Conditions		Symbol	Min	Max	Unit
Drain-source Voltage			V_{DS}	-	600	V
Gate-source Voltage			V_{GS}	-30	30	
Continuous Drain Current (Note 1,2)	Steady-State	$T_A=25^{\circ}C, V_{GS}=10V$	I_D	-	1.45	A
		$T_A=100^{\circ}C, V_{GS}=10V$		-	0.92	
Continuous Drain Current (Note 1,3)	Steady-State	$T_C=25^{\circ}C, V_{GS}=10V$		-	11	
		$T_C=100^{\circ}C, V_{GS}=10V$		-	6.95	
Pulsed Drain Current	$T_C=25^{\circ}C, t_p \leq 10\mu s$		I_{DM}	-	44	
Maximum Body-Diode Continuous Current	$T_C=25^{\circ}C$		I_S		11	
Maximum Body-Diode Pulsed Current	$T_C=25^{\circ}C, t_p \leq 10\mu s$		I_{SM}	-	44	
Avalanche Energy (non-repetitive)	$T_J=25^{\circ}C, V_G=10V, R_G=25\Omega, L=30mH, I_{AS}=2.8A$		EAS	-	117.6	mJ
Total Power Dissipation (Note 1,2)	Steady-State	$T_A=25^{\circ}C$	P_D	-	1.92	W
		$T_A=100^{\circ}C$		-	0.77	
Total Power Dissipation (Note 1,3)	Steady-State	$T_C=25^{\circ}C$		-	52	
		$T_C=100^{\circ}C$		-	20.8	
MOSFET dv/dt Ruggedness	$T_J=25^{\circ}C, V_{DS}=0 \dots 300V, I_D=11A, R_g=0\Omega$		dv/dt	-	107	V/ns
Reverse Diode dv/dt	$T_J=25^{\circ}C, V_{DS}=0 \dots 300V, I_D=11A, di/dt=100A/us$		dv/dt	-	34	
Maximum Diode Commutation Speed	$T_J=25^{\circ}C, V_{DS}=0 \dots 300V, I_D=11A, R_g=0\Omega$		dif/dt	-	4200	A/us
Insulation withstand voltage	$T_J=25^{\circ}C, V_{rms}, t=60s$		V_{ISO}	-	1	KV
Junction and Storage Temperature Range			T_J, T_{STG}	-55	150	$^{\circ}C$

Thermal Resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	Steady-State	$R_{\theta JA}$	-	65	$^{\circ}C/W$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	-	2.4	



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■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA, T _j =25°C	600	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =600V, V _{GS} =0V, T _j =25°C	-	-	1	μA
		V _{DS} =600V, V _{GS} =0V, T _j =125°C	-	-	100	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V, T _j =25°C	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA, T _j =25°C	2.7	3.5	4.3	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =5.5A, T _j =25°C	-	300	360	mΩ
		V _{GS} =10V, I _D =5.5A, T _j =150°C	-	757	908	
Diode Forward Voltage	V _{SD}	I _S =11A, V _{GS} =0V, T _j =25°C	-	0.91	1.2	V
Gate Resistance	R _G	f=1MHz, T _j =25°C	-	5.4	-	Ω
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =300V, V _{GS} =0V, f=1MHz, T _j =25°C	-	530	-	pF
Output Capacitance	C _{oss}		-	18.2	-	
Reverse Transfer Capacitance	C _{rss}		-	1.7	-	
Effective Output capacitance, Energy Related	C _{o(er)}	V _{DS} =0...300V, V _{GS} =0V, f=1MHz, T _j =25°C	-	34	-	
Effective Output Capacitance, Time Related	C _{o(tr)}		-	190	-	
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =300V, I _D =11A, T _j =25°C	-	16.3	-	nC
Gate-Source Charge	Q _{gs}		-	3.4	-	
Gate-Drain Charge	Q _{gd}		-	8.5	-	
Reverse Recovery Charge	Q _{rr}	I _F =11A, di/dt=100A/μs, V _{GS} =0V, V _R =300V, T _j =25°C	-	2580	-	nC
Reverse Recovery Time	t _{rr}		-	220	-	ns
Peak Reverse Recovery Current	I _{rrm}		-	23.7	-	A
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DS} =300V, I _D =11A, R _{GEN} =3Ω, T _j =25°C	-	31.5	-	ns
Turn-on Rise Time	t _r		-	12.6	-	
Turn-off Delay Time	t _{D(off)}		-	17.5	-	
Turn-off Fall Time	t _f		-	12.4	-	

Note:

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. The value of $R_{\theta JA}$ is measured in the still air environment with $T_A=25^\circ C$. The maximum allowed junction temperature of $150^\circ C$.
3. Thermal resistance from junction to soldering point (on the exposed drain pad).



■ Typical Electrical and Thermal Characteristics Diagrams

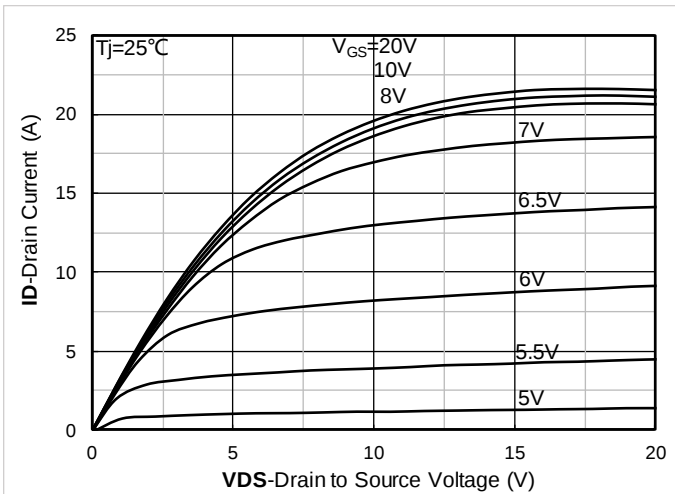


Figure 1. Output Characteristics; typical values

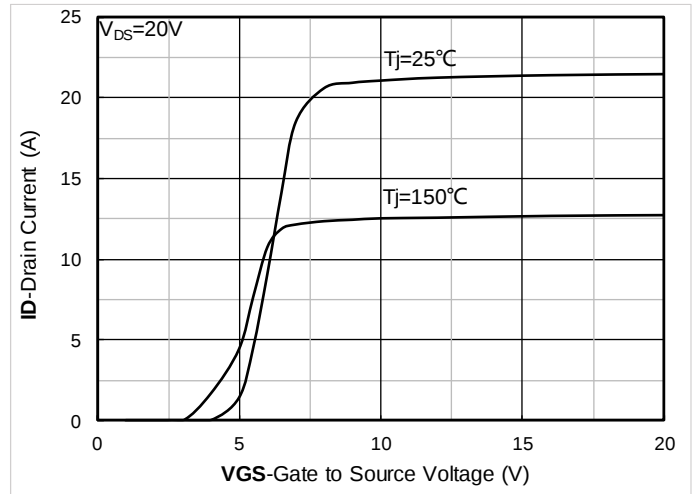


Figure 2. Transfer Characteristics; typical values

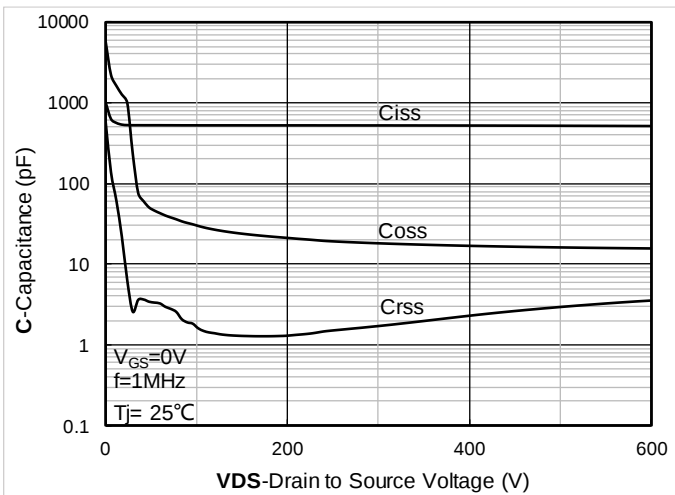


Figure 3. Capacitance Characteristics; typical values

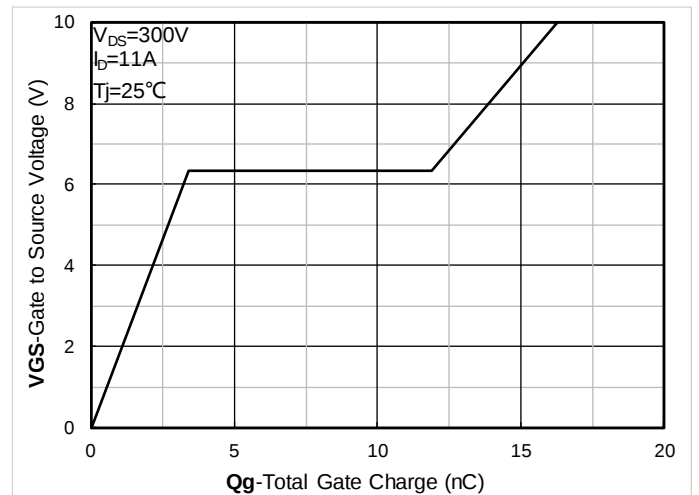


Figure 4. Gate Charge; typical values

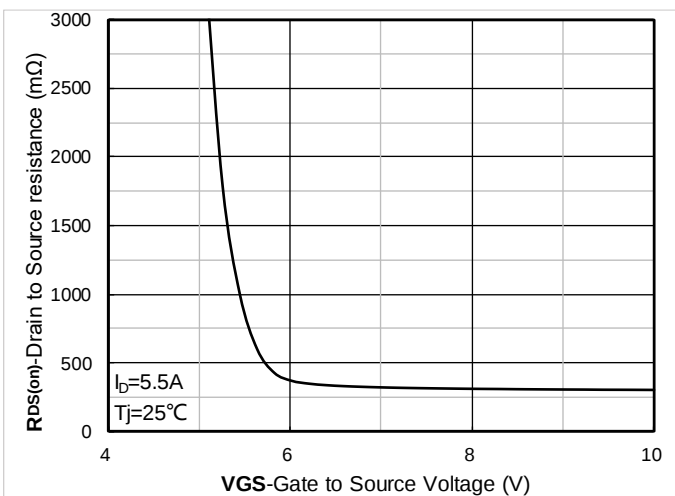


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

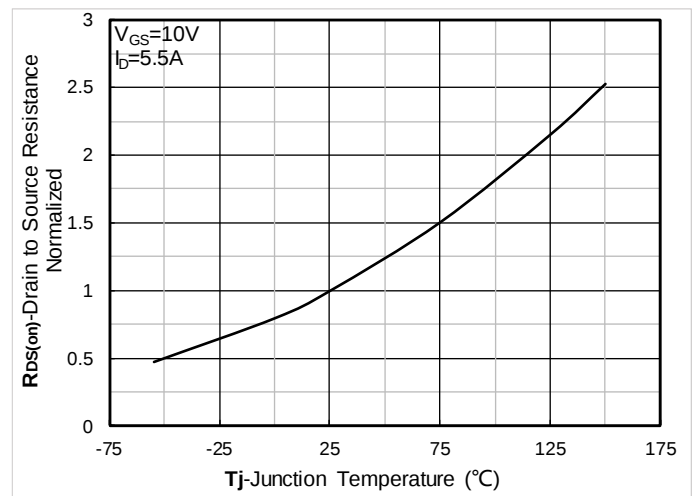


Figure 6. Normalized On-Resistance



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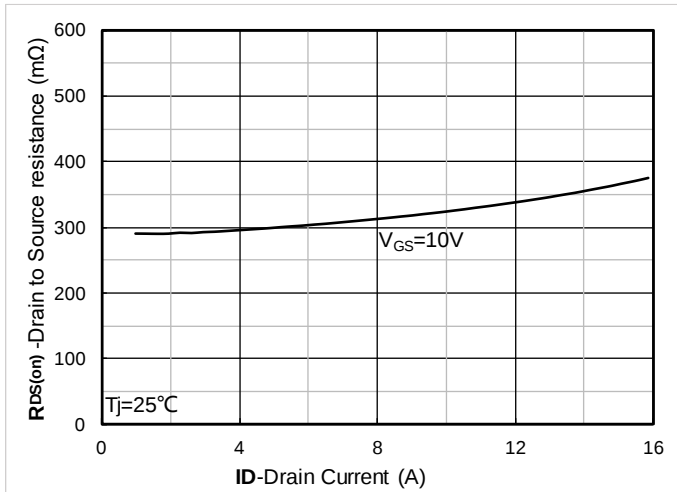


Figure 7. RDS(on) vs. Drain Current; typical values

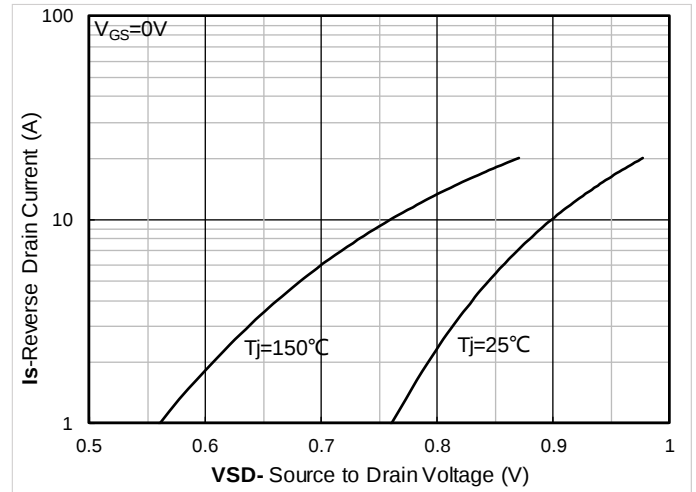


Figure 8. Forward characteristics of reverse diode; typical values

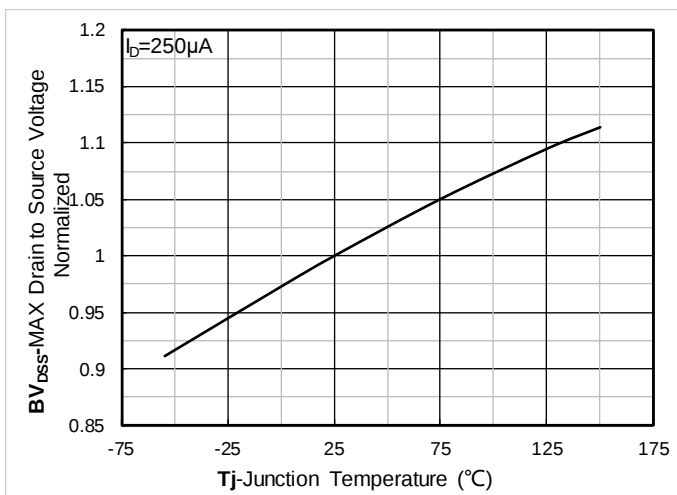


Figure 9. Normalized breakdown voltage

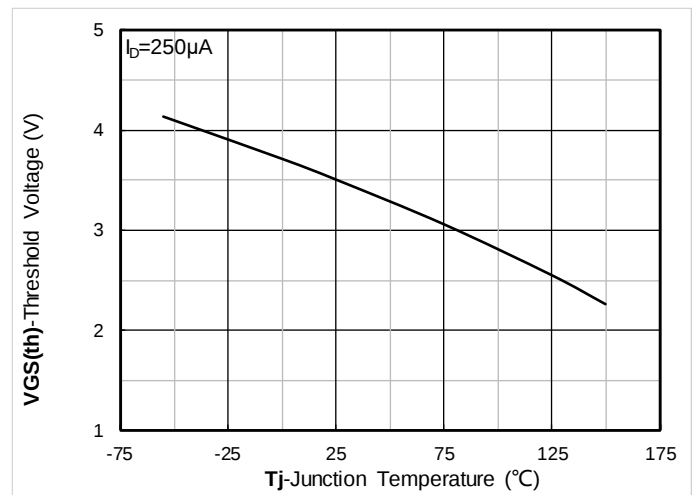


Figure 10. Gate Threshold voltage; typical values

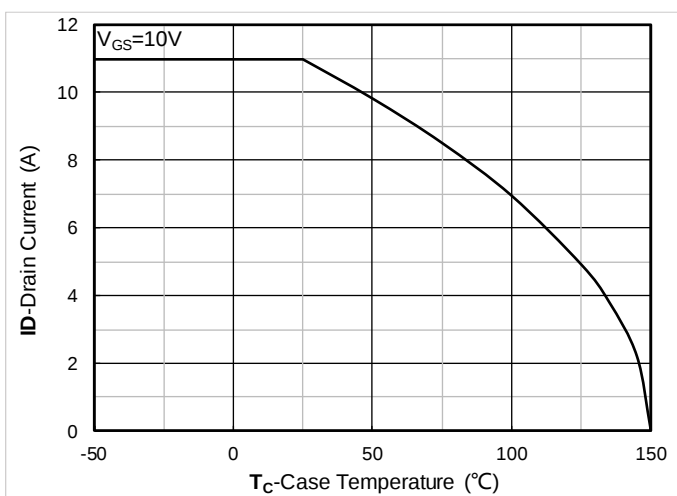


Figure 11. Current dissipation

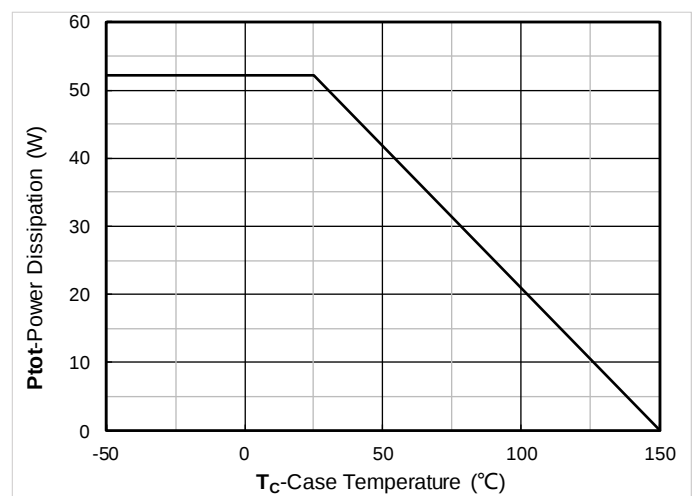


Figure 12. Power dissipation

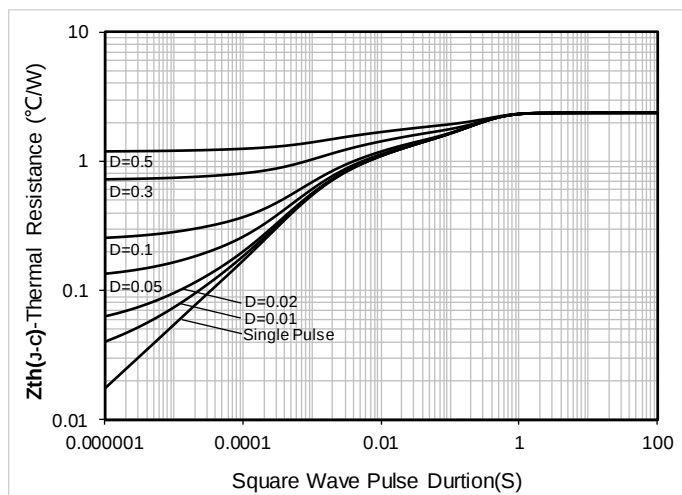


Figure 13. Maximum Transient Thermal Impedance

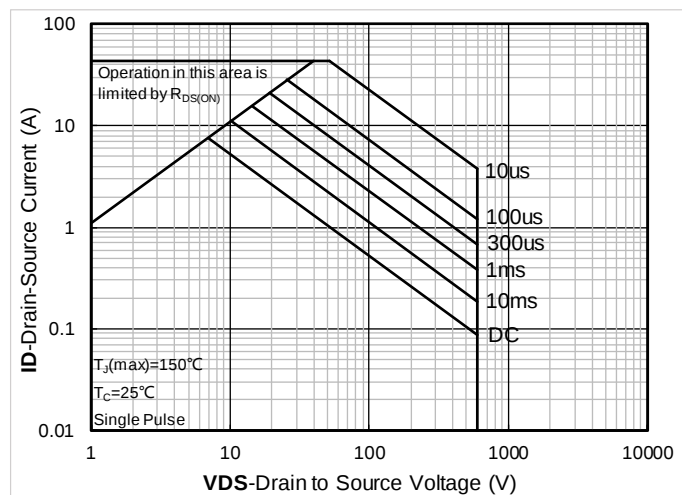


Figure 14. Safe Operation Area

■ Test Circuits & Waveforms

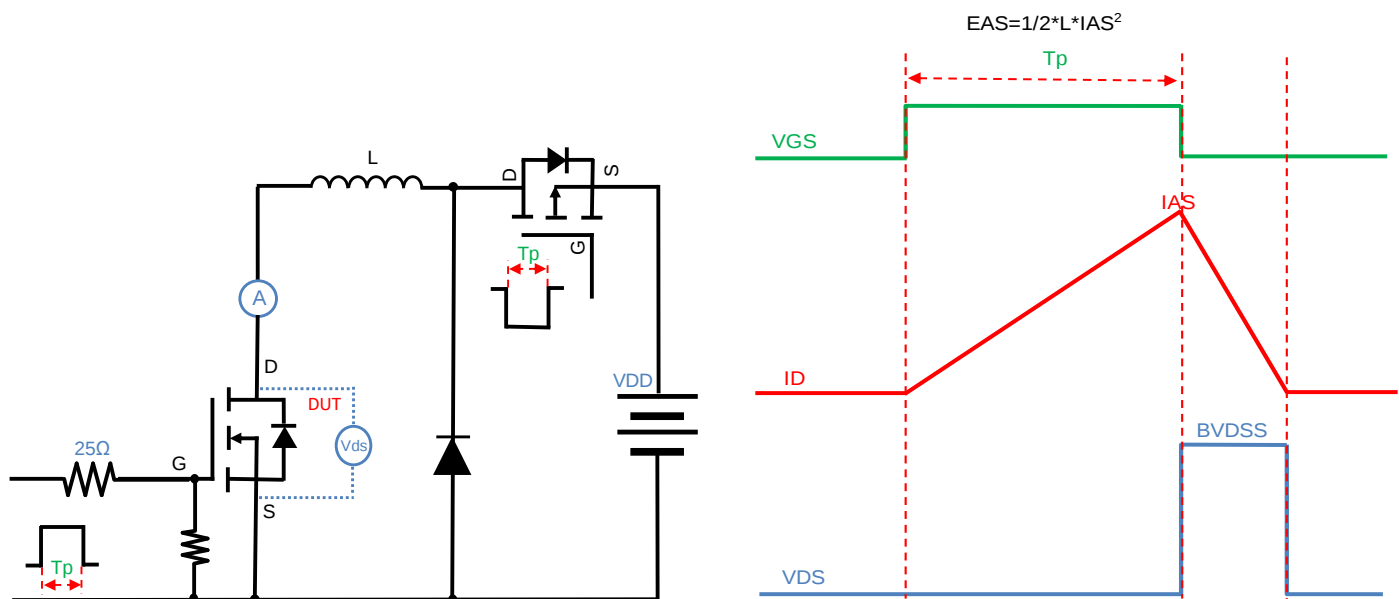


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

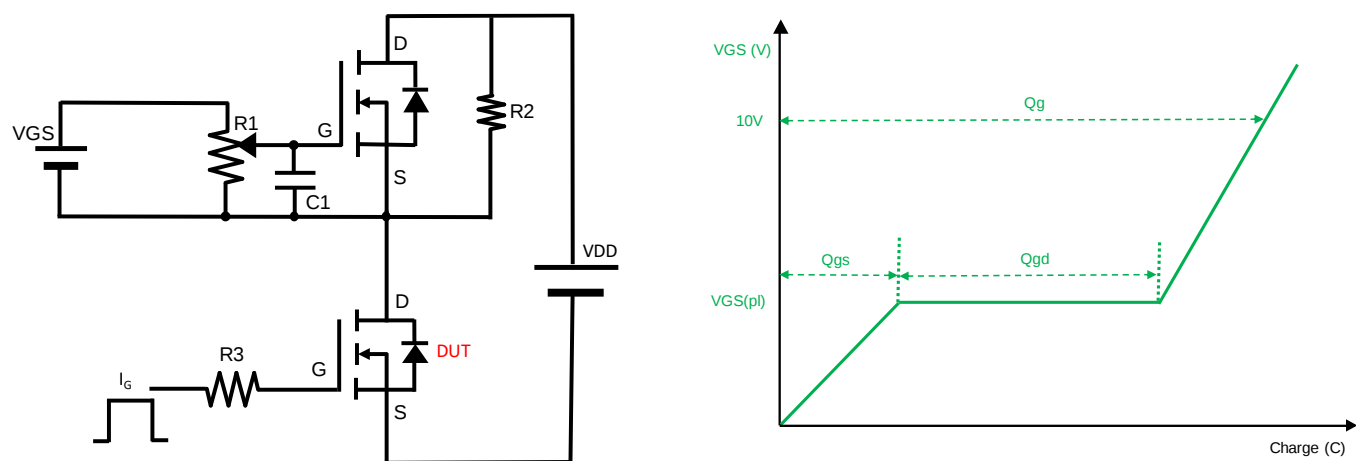


Figure B. Gate Charge Test Circuit & Waveform

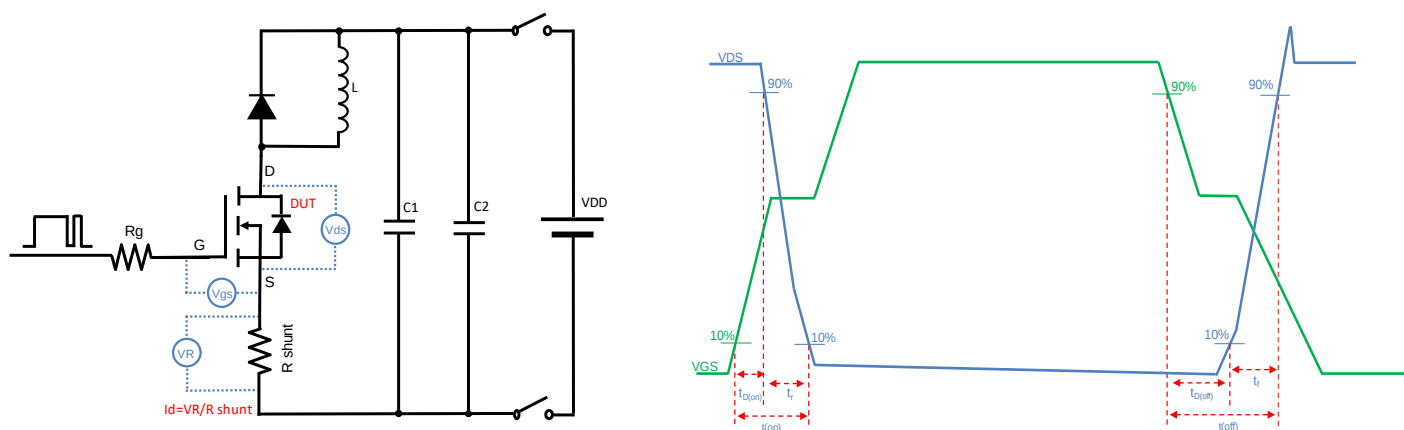


Figure C. Resistive Switching Test Circuit & Waveform

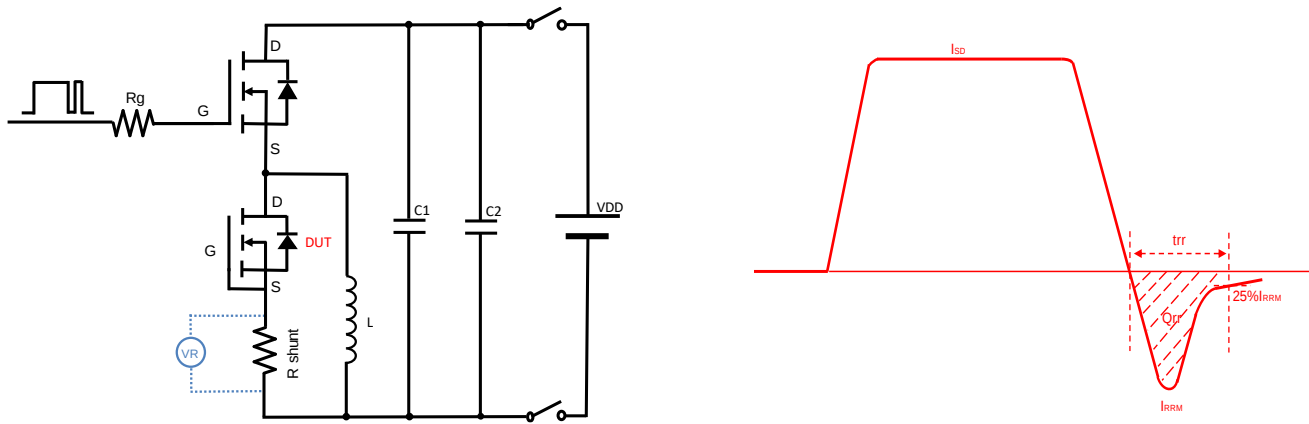
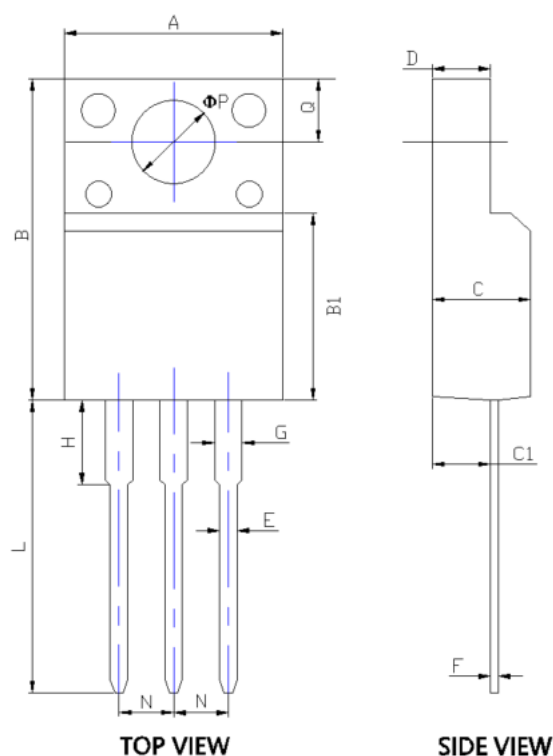


Figure D. Diode Recovery Test Circuit & Waveform



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■ ITO-220AB-E Package information

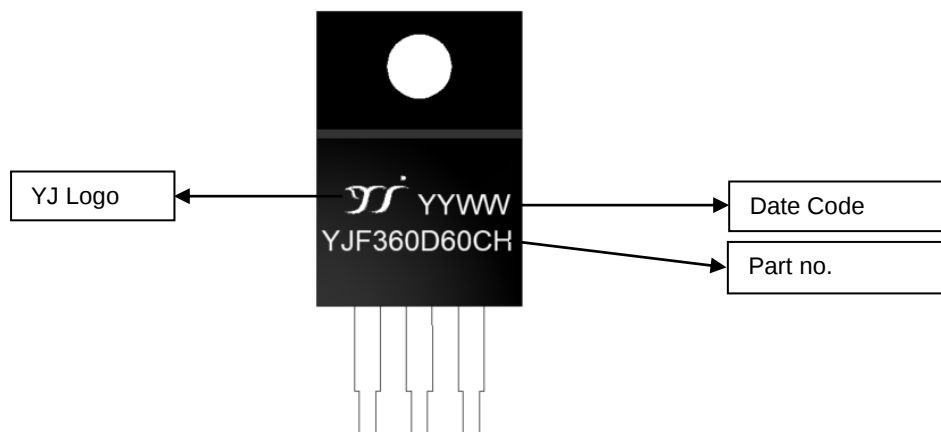


SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.390	0.406	9.900	10.300
B	0.610	0.633	15.500	16.100
B1	0.350	0.374	8.900	9.500
C	0.181	0.189	4.600	4.800
C1	0.087	0.110	2.200	2.800
D	0.096	0.104	2.450	2.650
E	0.028	0.035	0.700	0.900
F	0.016	0.024	0.400	0.600
G	0.044	0.056	1.120	1.420
H	0.134	0.150	3.400	3.800
L	0.496	0.512	12.600	13.000
N	0.100BSC.		2.540BSC.	
Q	0.126	0.142	3.200	3.600
ΦP	0.122	0.130	3.100	3.300

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.

■ Marking Information



Note:

1. All marking is at middle of the product body
2. All marking is in laser printing
3. YJF360D60CH is part no., YYWW is date code, "YY" is year, "WW" is week
4. Body color: Black



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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

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